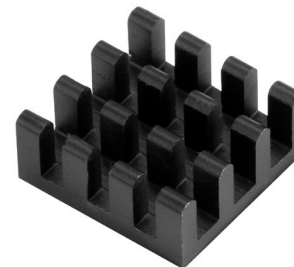


MODEL: HSB03-141406 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- small footprint
- aluminum alloy
- black anodized finish



MODEL

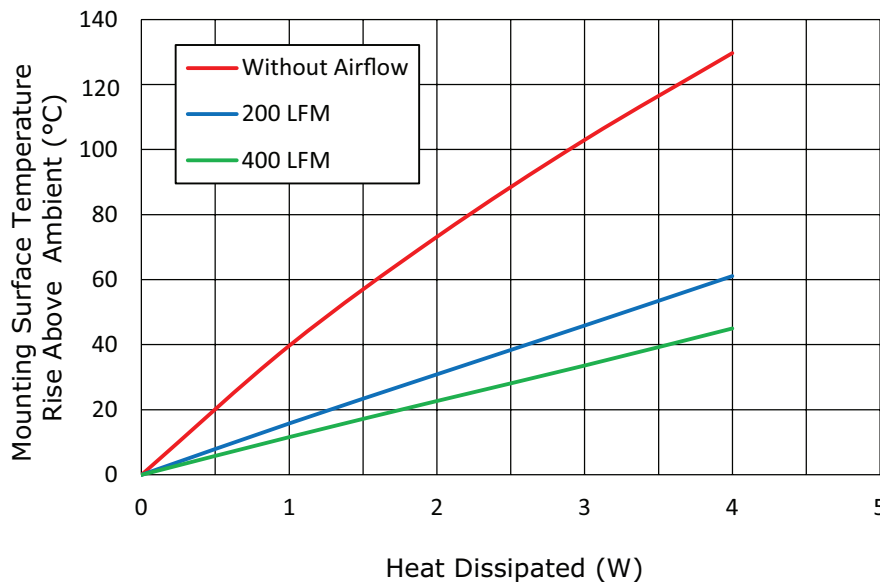
	thermal resistance ¹			power dissipation ¹ @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	
HSB03-141406	35.98	39.7	15.8	11.6

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	39.7	15.8	11.6
2	73.2	30.9	22.7
3	103.0	45.9	33.6
4	129.7	61.1	45.0

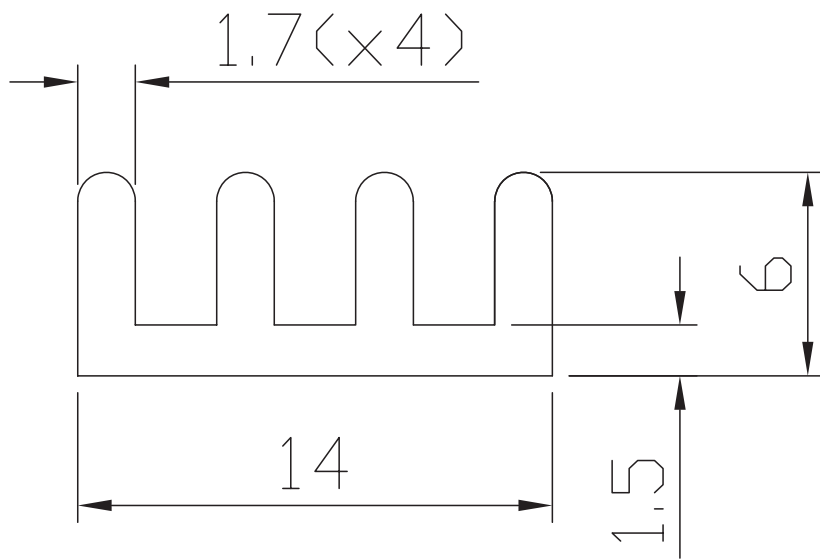
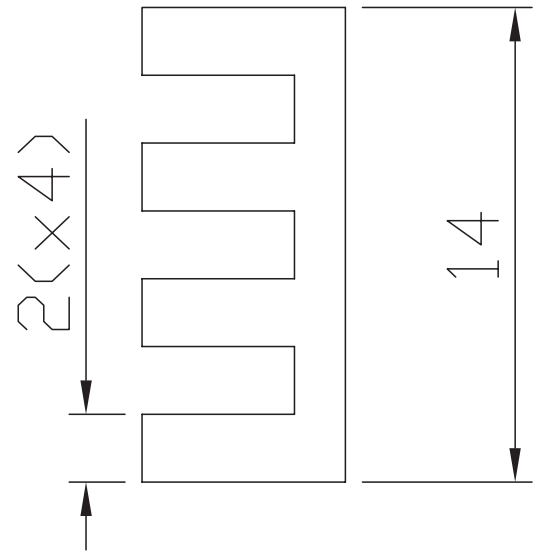
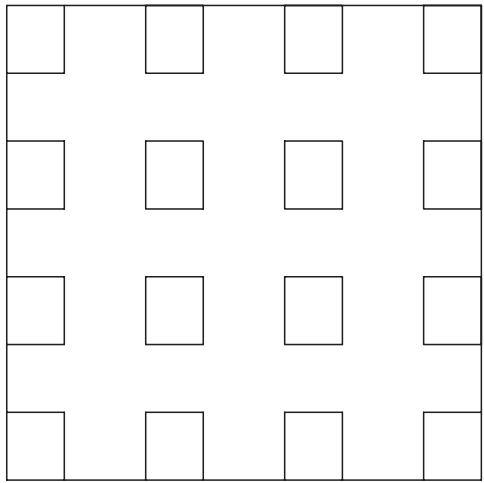
T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ± 0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	1.6 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/24/2021
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.



CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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